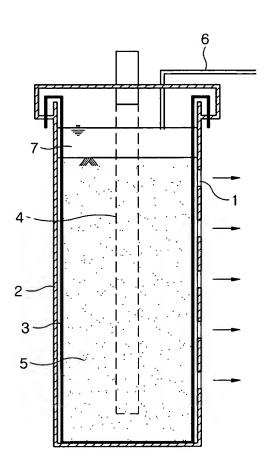
Express Mail No.: EL747202543US
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Title: Additive Injection System for In-Situ Soil
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FIG.1



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FIG.2

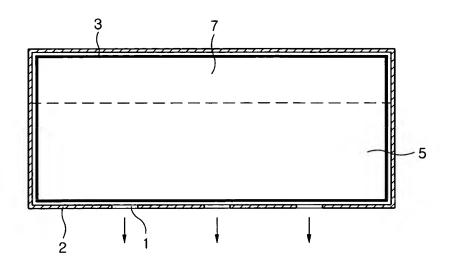
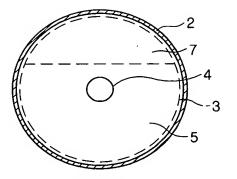
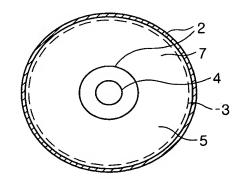


FIG.3



(A) Horizontal system



(B) Vertical and Horizontal system

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FIG.4

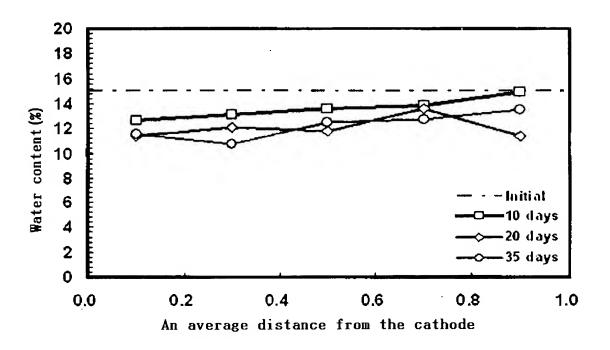


FIG.5

